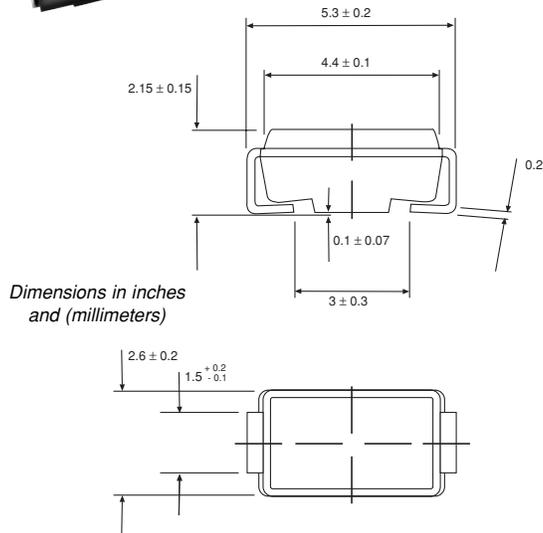
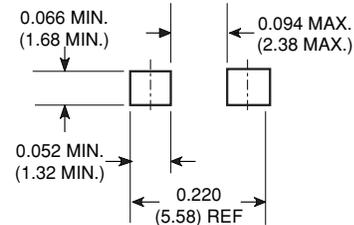


**DO-214AC
(SMA)**

Schottky Barrier Rectifiers

**Reverse Voltage 90
Forward Current 1.0A**

Mounting Pad Layout



Mechanical Data

Case: JEDEC DO-214AC molded plastic body
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
High temperature soldering guaranteed: 250°C/10 seconds at terminals
Polarity: Color band denotes cathode end
Weight: 0.002oz., 0.064g

Features

- Low power loss, high efficiency
- Low profile surface mount package
- Built-in strain relief
- Very low switching losses
- Low reverse current
- High surge capability
- Guardring for overvoltage protection
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0

Maximum Ratings and Thermal Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Symbol	BYS12-90	Unit
Device marking code		BYS 209	
Maximum repetitive peak reverse voltage	V _{RRM}	90	V
Maximum average forward rectified current	I _{F(AV)}	1.5	A
Peak forward surge current single half sine-wave superimposed on rated load	I _{FSM}	40 30	A
Maximum Thermal Resistance – Junction Ambient	R _{θJA}	150 ⁽¹⁾ 125 ⁽²⁾ 100 ⁽³⁾	°C/W
Voltage rate of change (V _R)	dv/dt	10,000	V/μs
Junction and storage temperature range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Maximum instantaneous forward voltage at: ⁽⁴⁾	I _F = 1A I _F = 15mA	V _F	750 360	mV
Maximum DC reverse current at V _{RRM} ⁽⁴⁾	T _J = 25°C T _J = 100°C	I _R	100 1	μA mA

Notes: (1) Mounted on epoxy-glass hard tissue
 (2) Mounted on epoxy-glass hard tissue, 50 mm² 35 μm Cu
 (3) Mounted on Al-oxide-ceramic (Al₂O₃), 50 mm² 35 μm Cu
 (4) Pulse test: 300μs pulse width, 1% duty cycle



Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Forward Current vs. Forward Voltage

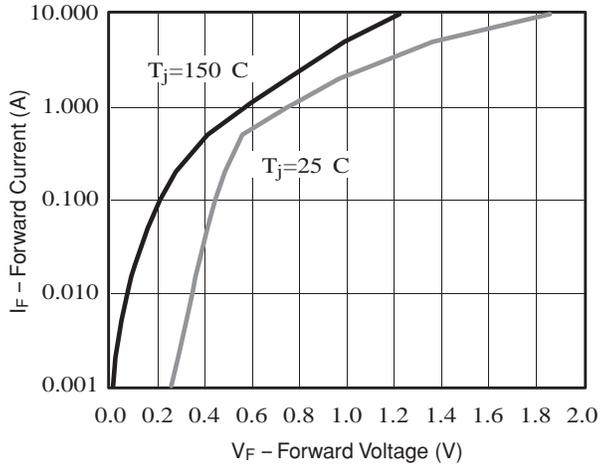


Fig. 4 – Reverse Current vs. Junction Temperature

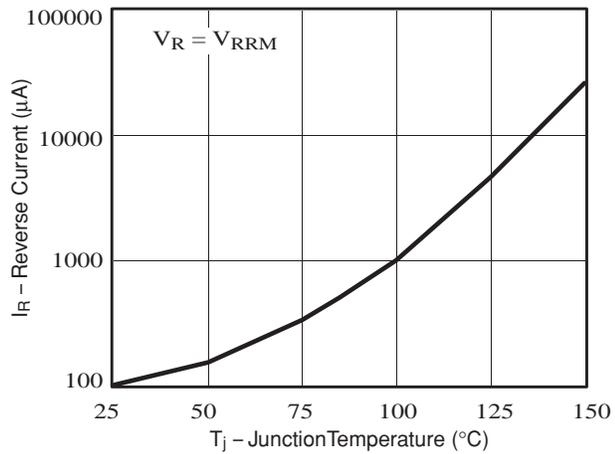


Fig. 2 – Max. Average Forward Current vs. Ambient Temperature

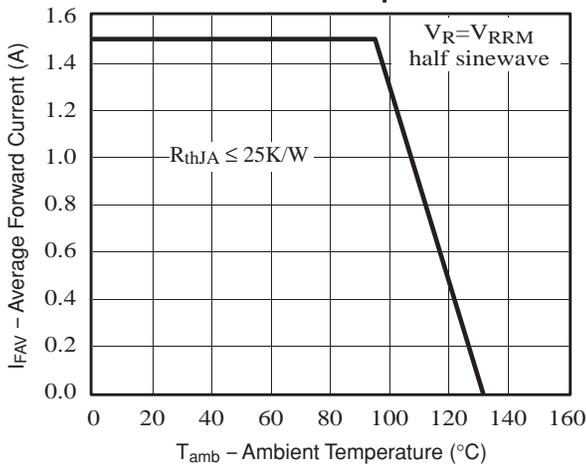


Fig. 5 – Max. Reverse Power Dissipation vs. Junction Temperature

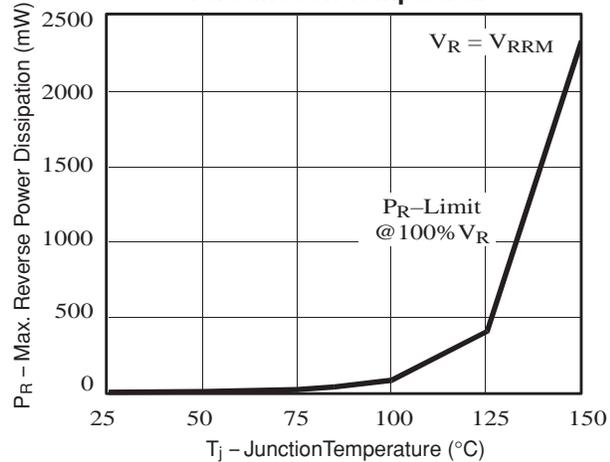


Fig. 3 – Max. Average Forward Current vs. Ambient Temperature

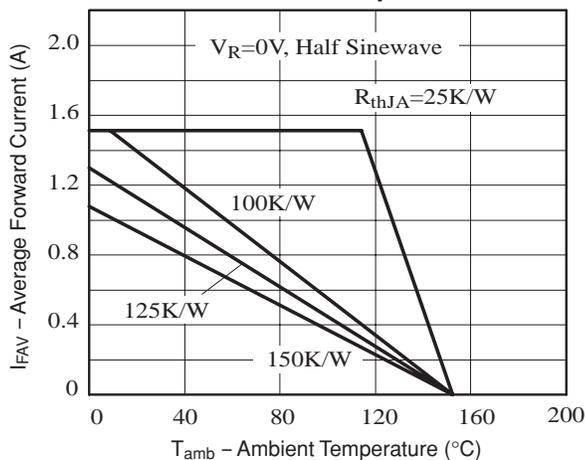
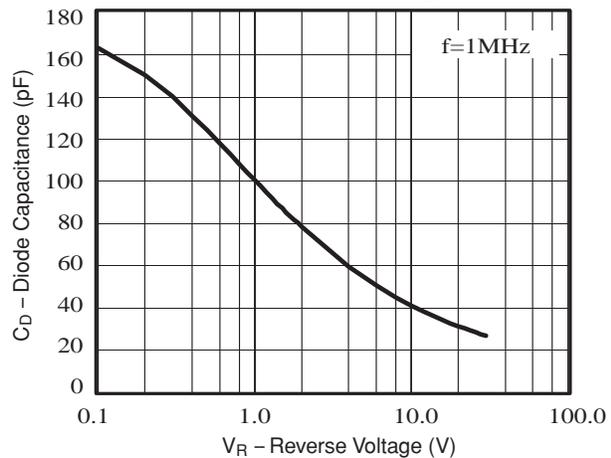


Fig. 6 – Diode Capacitance vs. Reverse Voltage





Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.